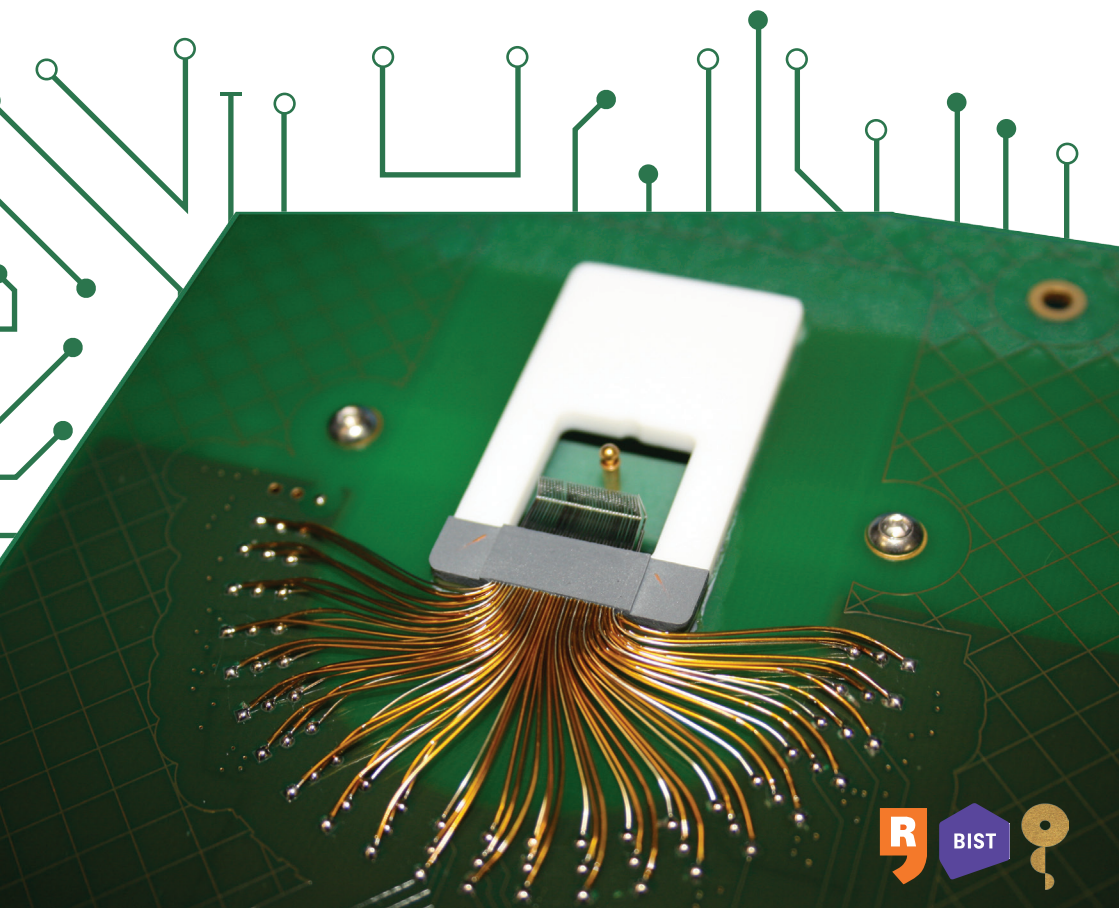


FROM PARTICLES TO THE COSMOS

FAIR

MICROELECTRONIC SERVICES



IFAE MICROELECTRONICS LABORATORY

IFAE has wide experience, know-how and singular infrastructure for ASIC design, FPGA and microcontroller programming and ASIC, FPGA and microcontroller assembly.

The IFAE Microelectronics laboratory is equipped with state-of-the-art packaging and assembly technologies, including **bump deposition, flip-chip, automated wire-bonding** and **inspection systems**.

WE COVER THE WHOLE **MICROELECTRONICS ASSEMBLY PROCESS** INCLUDING DESIGN, PROTOTYPING AND QUALITY CONTROL

ASSEMBLY LINE

SOLDER BUMP
DEPOSITION



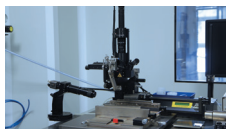
BUMP
BONDING



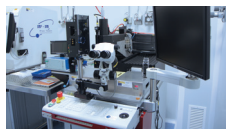
REFLOW
OVEN



DEVICE
ASSEMBLY



WIRE
BONDING



QUALITY CONTROL

X-RAY
INSPECTION

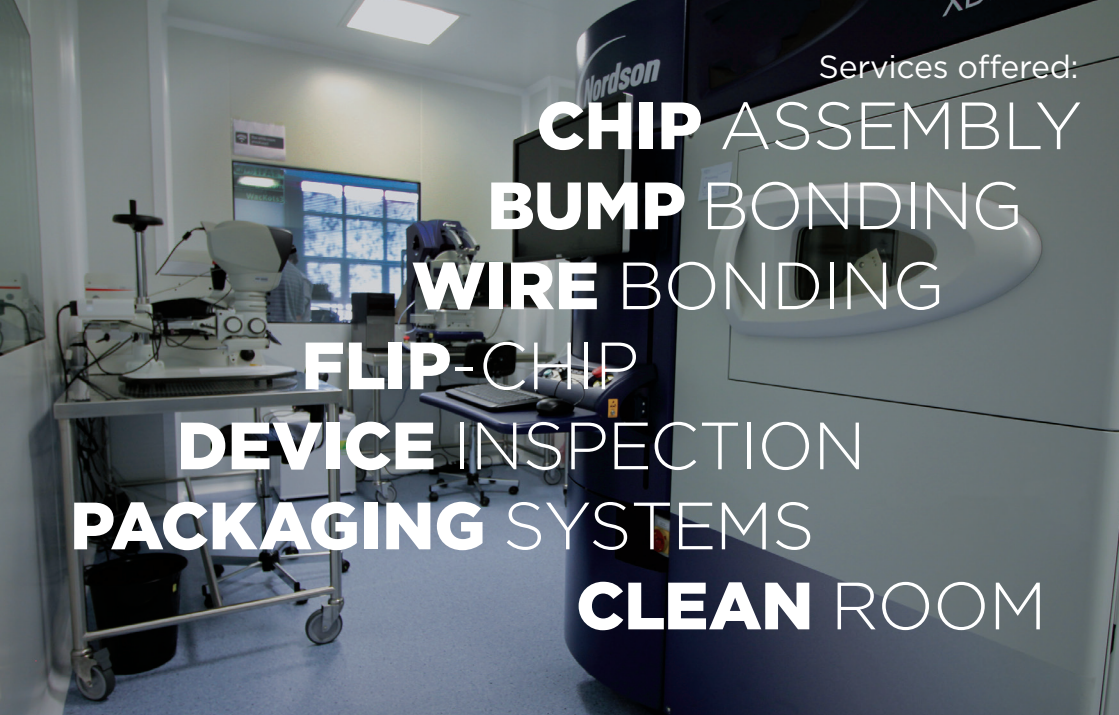


PROBE
STATION



PULL & SHEAR
BOND TESTER





Services offered:

CHIP ASSEMBLY
BUMP BONDING
WIRE BONDING
FLIP-CHIP
DEVICE INSPECTION
PACKAGING SYSTEMS
CLEAN ROOM

WE OFFER **SOLUTIONS** IN THE FIELD
OF **RADIATION & PARTICLE DETECTORS**
BASED ON TAILORED ELECTRONICS &
MICROELECTRONICS TECHNOLOGY

CUSTOMERS



PROJECTS

We also offer **collaborative research** with industry in the framework of public funding at national and international level.

- Pixel detector development, including readout and front-end electronics
- X-Ray, Nuclear Medicine and IR-Vis Camera design and construction
- High precision mechanics, electronics, optics & control software



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